

ABSTRACT OF THE DISCLOSURE

A method for fabricating a circuit module includes a step of filling the gap between a chip component and a substrate on which the chip component is mounted in a flip chip configuration with resin. The method uses simplified equipment and minimizes the undesired spread of resin. The resin is supplied between the sidewall of a dispenser needle and the sidewall of the chip component. Due to capillary action, a resin pool is formed and then the gap between the chip component and the substrate is spontaneously filled with the resin of the resin pool.